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**UPDATE CHANGE NOTIFICATION # 16382**Generic Copy

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**Issue Date:** 21-Jul-2011**TITLE:** 2N7002L Product types with Trench Die**PROPOSED FIRST SHIP DATE:** 15-Aug-2011**AFFECTED CHANGE CATEGORY(S):** Wafer Fabrication**AFFECTED PRODUCT DIVISION:** PowerFET Business Unit**ADDITIONAL RELIABILITY DATA:** Contact your local ON Semiconductor Sales Office Office or Donna Scheuch<[d.scheuch@onsemi.com](mailto:d.scheuch@onsemi.com)>**SAMPLES:** Contact your local ON Semiconductor Sales Office or Brian Goodburn <[brian.goodburn@onsemi.com](mailto:brian.goodburn@onsemi.com)>**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Jason Jeong <[Jason.Jeong@onsemi.com](mailto:Jason.Jeong@onsemi.com)>**NOTIFICATION TYPE:**ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.**DESCRIPTION AND PURPOSE:**

Referencing FPCN # 16382: 2N7002L Product types with Trench Die

This is an updated notification on FPCN #16382 announcing to Customers that ON Semiconductor is revising their effective timeline for changing the Die technology on their 2N7002L product types. Products will now have a Date Code of the Work Week 34, 2011 or newer.

**List of affected General Parts:**2N7002LT1G  
2N7002LT1H  
2N7002LT1  
2N7002LT3G  
2N7002LT3H  
2N7002LT3